

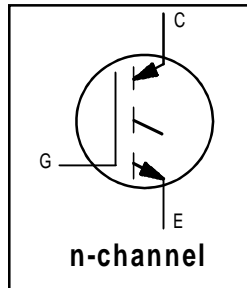
IRG4BC30U-S

INSULATED GATE BIPOLAR TRANSISTOR

UltraFast Speed IGBT

Features

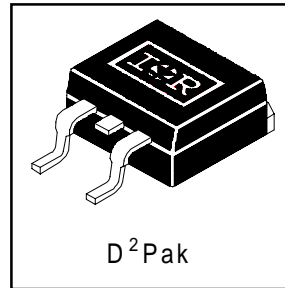
- UltraFast: Optimized for high operating frequencies 8-40 kHz in hard switching, >200 kHz in resonant mode
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than Generation 3
- Industry standard D²Pak package



| |
|-----------------------------------|
| $V_{CES} = 600V$ |
| $V_{CE(on)} \text{ typ.} = 1.95V$ |
| @ $V_{GE} = 15V, I_C = 12A$ |

Benefits

- Generation 4 IGBT's offer highest efficiency available
- IGBT's optimized for specified application conditions
- Designed to be a "drop-in" replacement for equivalent industry-standard Generation 3 IR IGBT's



Absolute Maximum Ratings

| | Parameter | Max. | Units |
|---------------------------|---|--------------|-------|
| V_{CES} | Collector-to-Emitter Breakdown Voltage | 600 | V |
| $I_C @ T_C = 25^\circ C$ | Continuous Collector Current | 23 | A |
| $I_C @ T_C = 100^\circ C$ | Continuous Collector Current | 12 | |
| I_{CM} | Pulsed Collector Current ① | 92 | |
| I_{LM} | Clamped Inductive Load Current ② | 92 | |
| V_{GE} | Gate-to-Emitter Voltage | ± 20 | V |
| E_{ARV} | Reverse Voltage Avalanche Energy ③ | 10 | mJ |
| $P_D @ T_C = 25^\circ C$ | Maximum Power Dissipation | 100 | W |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation | 42 | |
| T_J T_{STG} | Operating Junction and Storage Temperature Range | -55 to + 150 | |

Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|-----------------|--|------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case | — | 1.2 | $^\circ C/W$ |
| $R_{\theta JA}$ | Junction-to-Ambient, (PCB Mounted, steady-state)* | — | 40 | |

* When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------|---|------|------|-----------|----------------------|---|
| $V_{(BR)CES}$ | Collector-to-Emitter Breakdown Voltage | 600 | — | — | V | $V_{GE} = 0V, I_C = 250\mu\text{A}$ |
| $V_{(BR)ECS}$ | Emitter-to-Collector Breakdown Voltage ^④ | 18 | — | — | V | $V_{GE} = 0V, I_C = 1.0A$ |
| $DV_{(BR)CES/DT_J}$ | Temperature Coeff. of Breakdown Voltage | — | 0.63 | — | V/ $^\circ\text{C}$ | $V_{GE} = 0V, I_C = 1.0mA$ |
| $V_{CE(ON)}$ | Collector-to-Emitter Saturation Voltage | — | 1.95 | 2.1 | V | $I_C = 12A$ $V_{GE} = 15V$ See Fig.2, 5 |
| | | — | 2.52 | — | | |
| | | — | 2.09 | — | | |
| $V_{GE(th)}$ | Gate Threshold Voltage | 3.0 | — | 6.0 | | $V_{CE} = V_{GE}, I_C = 250\mu\text{A}$ |
| $DV_{GE(th)/DT_J}$ | Temperature Coeff. of Threshold Voltage | — | -13 | — | mV/ $^\circ\text{C}$ | $V_{CE} = V_{GE}, I_C = 250\mu\text{A}$ |
| g_{fe} | Forward Transconductance ^⑤ | 3.1 | 8.6 | — | S | $V_{CE} = 100V, I_C = 12A$ |
| I_{CES} | Zero Gate Voltage Collector Current | — | — | 250 | μA | $V_{GE} = 0V, V_{CE} = 600V$ |
| | | — | — | 2.0 | | $V_{GE} = 0V, V_{CE} = 10V, T_J = 25^\circ\text{C}$ |
| | | — | — | 1000 | | $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$ |
| I_{GES} | Gate-to-Emitter Leakage Current | — | — | ± 100 | nA | $V_{GE} = \pm 20V$ |

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------|-----------------------------------|------|------|------|-------|---|
| Q_g | Total Gate Charge (turn-on) | — | 50 | 75 | nC | $I_C = 12A$ $V_{CC} = 400V$ See Fig.8 $V_{GE} = 15V$ |
| Q_{ge} | Gate - Emitter Charge (turn-on) | — | 8.1 | 12 | | |
| Q_{gc} | Gate - Collector Charge (turn-on) | — | 18 | 27 | | |
| $t_{d(on)}$ | Turn-On Delay Time | — | 17 | — | ns | $T_J = 25^\circ\text{C}$ $I_C = 12A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 23\Omega$ Energy losses include "tail" See Fig. 10, 11, 13, 14 |
| t_r | Rise Time | — | 9.6 | — | | |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 78 | 120 | | |
| t_f | Fall Time | — | 97 | 150 | mJ | See Fig. 13, 14 |
| E_{on} | Turn-On Switching Loss | — | 0.16 | — | | |
| E_{off} | Turn-Off Switching Loss | — | 0.20 | — | | |
| E_{ts} | Total Switching Loss | — | 0.36 | 0.50 | ns | $T_J = 150^\circ\text{C},$ $I_C = 12A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 23\Omega$ Energy losses include "tail" |
| $t_{d(on)}$ | Turn-On Delay Time | — | 20 | — | | |
| t_r | Rise Time | — | 13 | — | | |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 180 | — | mJ | See Fig. 13, 14 |
| t_f | Fall Time | — | 140 | — | | |
| E_{ts} | Total Switching Loss | — | 0.73 | — | | |
| L_E | Internal Source Inductance | — | 7.5 | — | nH | Measured 5mm from package |
| C_{ies} | Input Capacitance | — | 1100 | — | pF | $V_{GE} = 0V$ $V_{CC} = 30V$ See Fig.7 $f = 1.0\text{MHz}$ |
| C_{oes} | Output Capacitance | — | 73 | — | | |
| C_{res} | Reverse Transfer Capacitance | — | 14 | — | | |

Notes:

- ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature. (See fig. 13b)
- ② $V_{CC} = 80\%(V_{CES}), V_{GE} = 20V, L = 10\mu\text{H}, R_G = 23\Omega,$ (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width $\leq 80\mu\text{s}$; duty factor $\leq 0.1\%$.
- ⑤ Pulse width $5.0\mu\text{s}$, single shot.

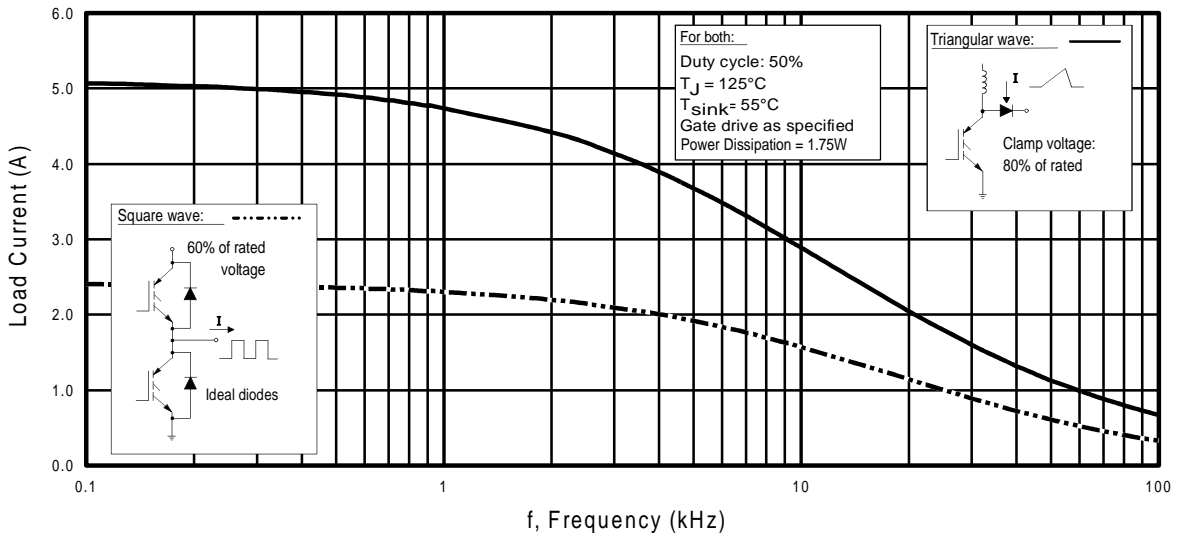


Fig. 1 - Typical Load Current vs. Frequency
(For square wave, $I = I_{\text{RMS}}$ of fundamental; for triangular wave, $I = I_{\text{PK}}$)

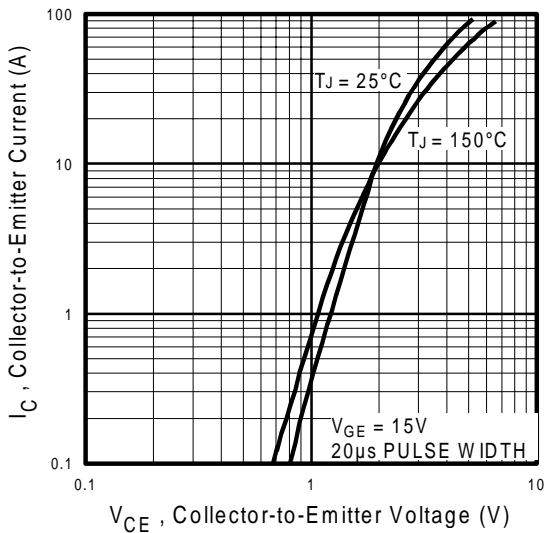


Fig. 2 - Typical Output Characteristics

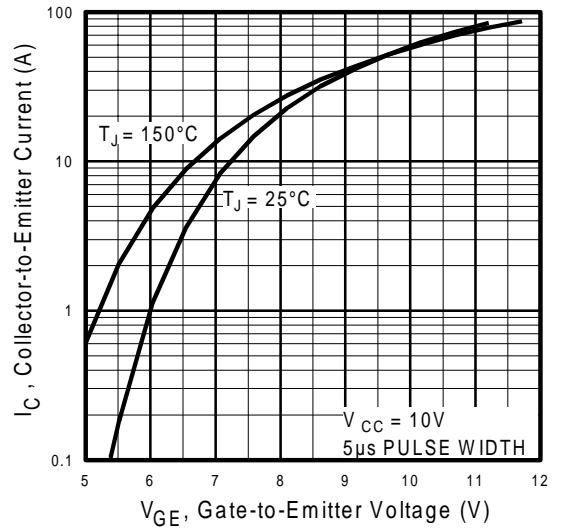


Fig. 3 - Typical Transfer Characteristics

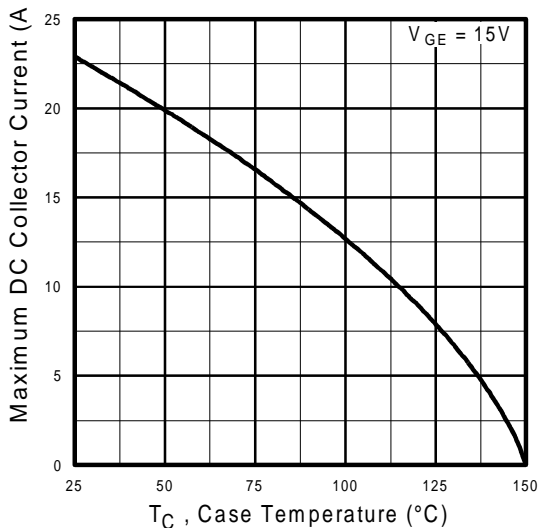


Fig. 4 - Maximum Collector Current vs. Case Temperature

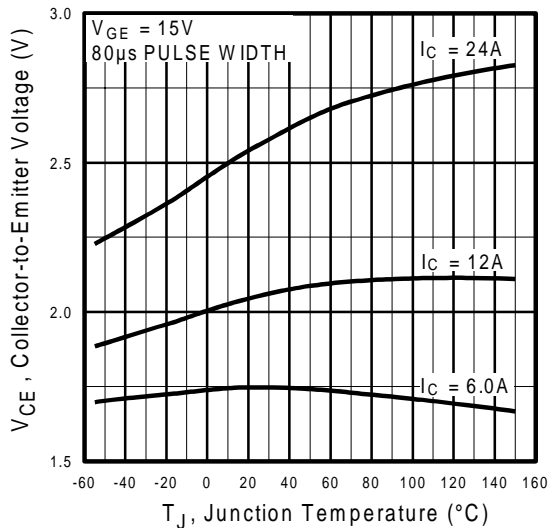


Fig. 5 - Collector-to-Emitter Voltage vs. Junction Temperature

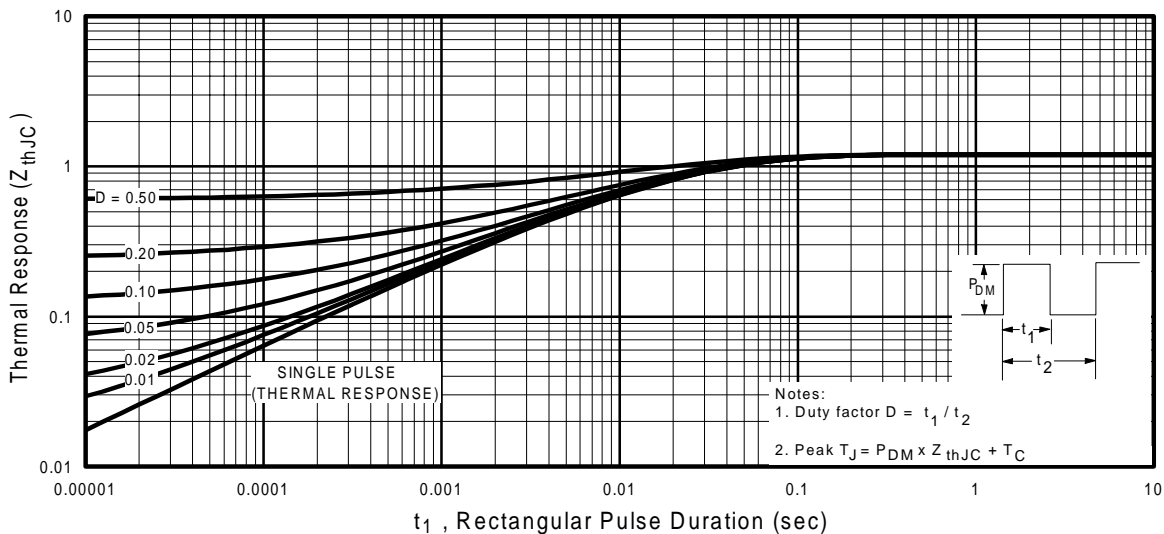


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

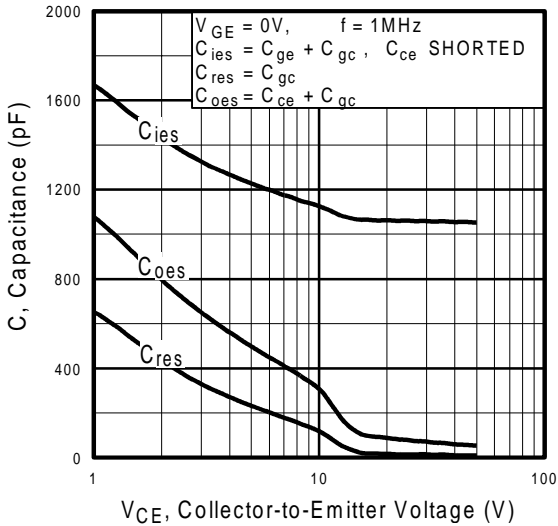


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

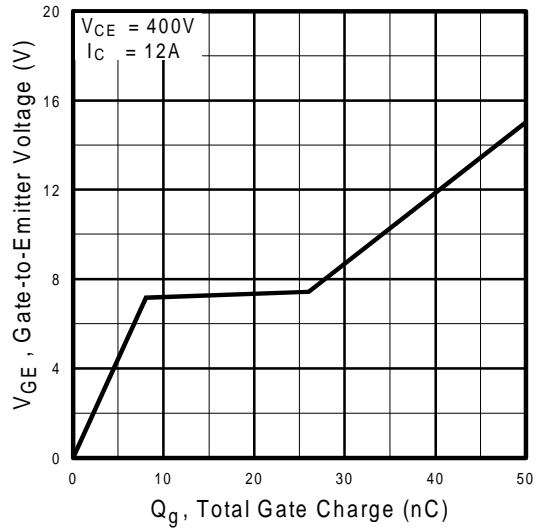


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

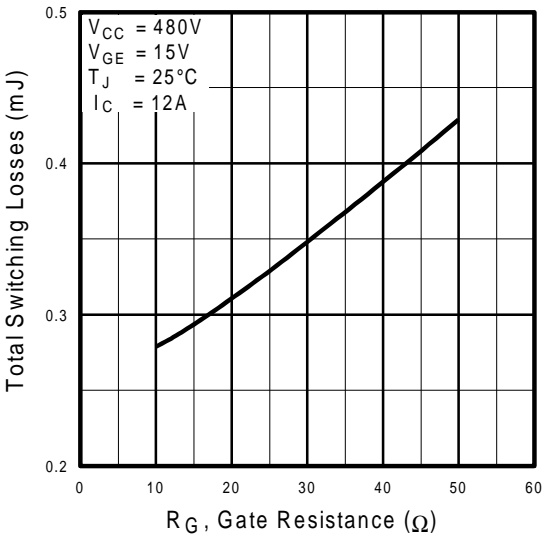


Fig. 9 - Typical Switching Losses vs. Gate Resistance

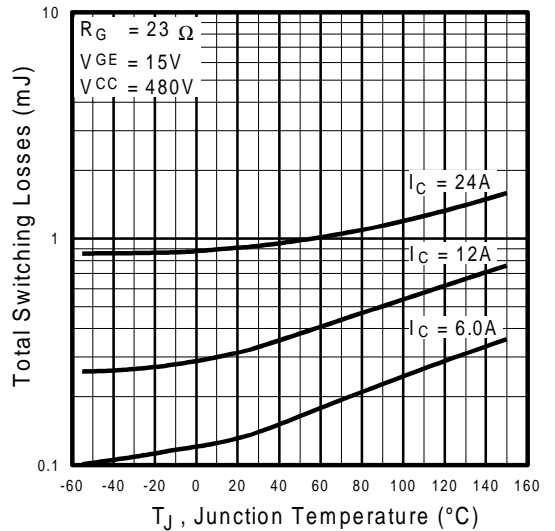


Fig. 10 - Typical Switching Losses vs. Junction Temperature

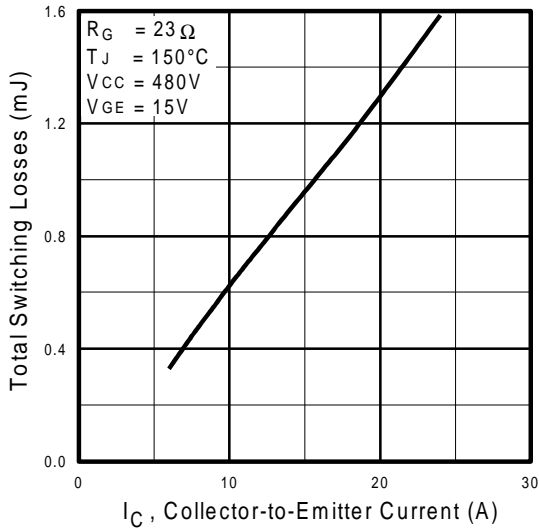


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

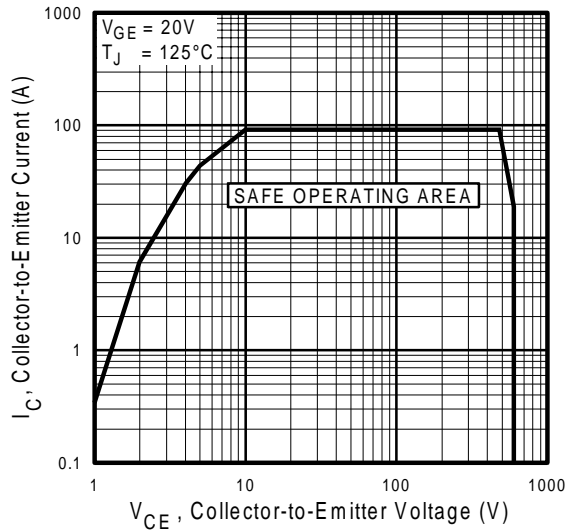


Fig. 12 - Turn-Off SOA

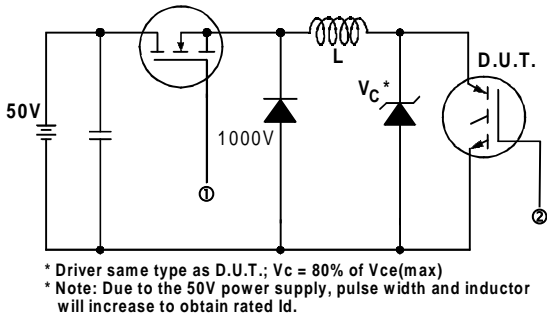


Fig. 13a - Clamped Inductive Load Test Circuit

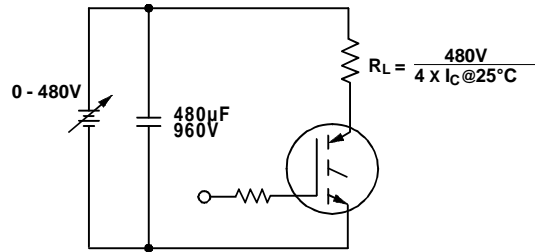


Fig. 13b - Pulsed Collector Current Test Circuit

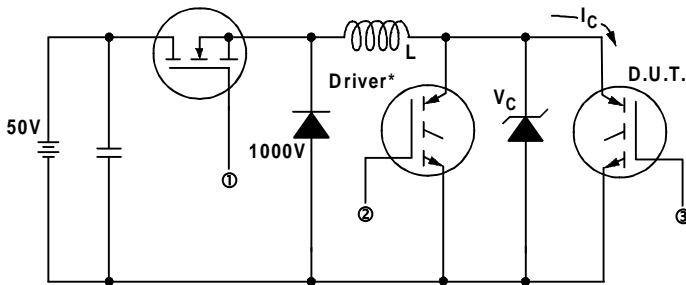


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_C = 480V$

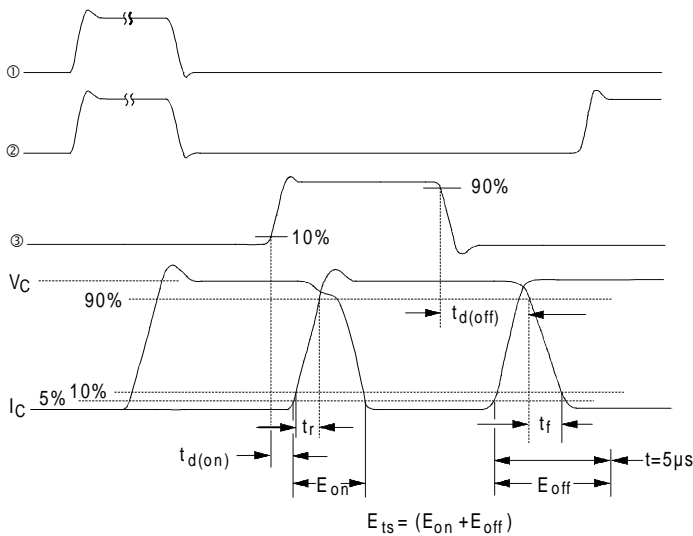
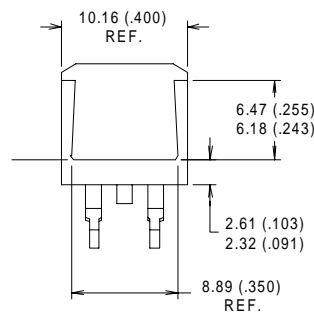
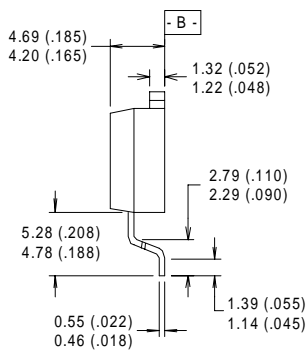
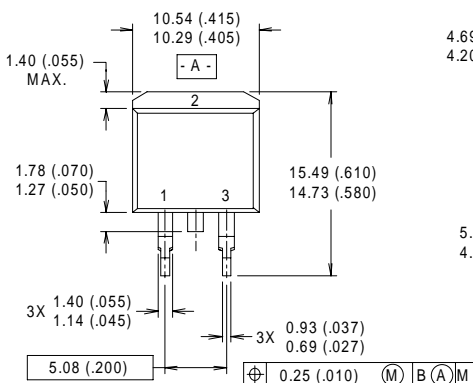
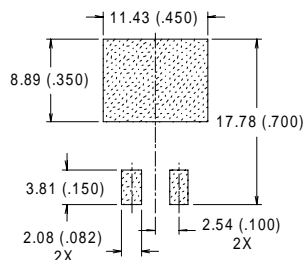


Fig. 14b - Switching Loss Waveforms

D²Pak Package Outline



MINIMUM RECOMMENDED FOOTPRINT



NOTES:

- 1 DIMENSIONS AFTER SOLDER DIP.
- 2 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
- 3 CONTROLLING DIMENSION : INCH.
- 4 HEATSINK & LEAD DIMENSIONS DO NOT INCLUDE BURRS.

LEAD ASSIGNMENTS

- 1 - GATE
- 2 - DRAIN
- 3 - SOURCE

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>